

## 1 Introduction

The i.MX RT series MCU is a crossover product from NXP. It includes a FlexSPI controller supporting HyperBus devices (HyperFlash/HyperRAM), Serial NOR Flash, or other device with similar SPI protocol as Serial NOR Flash, and so on.

*How to Enable HyperRAM with i.MX RT* (document [AN12239](#)) introduces the basic knowledge about how to enable HyperRAM with i.MX RT. This application note describes the advanced usage of HyperRAM/PSRAM when used with FlexSPI on i.MX RT MCU. The advantages include FlexSPI prefetch function, HyperRAM/PSRAM refresh interval, and HyperRAM devices supported for i.MX RT.

This application note uses i.MX RT1050 and RT1170 as examples. HyperRAM devices from different vendors and PSRAM device from Apmemory are used for test.

## 2 FlexSPI controller

Flexible Serial Peripheral Interface (FlexSPI) controller in i.MX RT1050 supports following features:

- Flexible sequence engine (LUT table) to support various vendor devices:
  - Serial NOR/NAND Flash
  - HyperBus device (HyperFlash/HyperRAM)
  - FPGA device
- Flash access mode:
  - Single/Dual/Quad/Octal mode
  - SDR/DDR mode
  - Individual/Parallel mode
- Memory mapped read/write access by AHB bus:
  - AHB RX buffer implemented to reduce read latency. Total AHB RX buffer size: 128 × 64 bits
  - Four flexible and configurable buffers in AHB RX buffer
  - AHB TX buffer implemented to buffer all write data from one AHB burst. AHB TX buffer size: 8 × 64 bits
- Software triggered Flash read/write access by IP bus:
  - IP RX FIFO implemented to buffer all read data from the external device. FIFO size: 16 × 64 bits
  - IP TX FIFO implemented to buffer all Write data to the external device. FIFO size: 16 × 64 bits

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### 3 HyperBus interface

FlexSPI controller can support HyperBus device, and HyperRAM is the device used with HyperBus interface.

HyperBus is a low signal count, Double Data Rate (DDR) interface, that achieves high-speed read and write throughput. Command, address, and data information are transferred over the eight HyperBus DQ[7:0] signals. The clock (CK#, CK) is used for information capture by a HyperBus slave device when receiving command, address, or data on the DQ signals. Command or Address values are center-aligned with clock transitions.

Every transaction begins with the assertion of CS# and Command-Address (CA) signals. It is followed by the start of clock transitions to transfer six CA bytes. It is also followed by initial access latency and either read or write data transfers, until CS# is de-asserted.

Figure 1 shows a read transaction with single latency count.

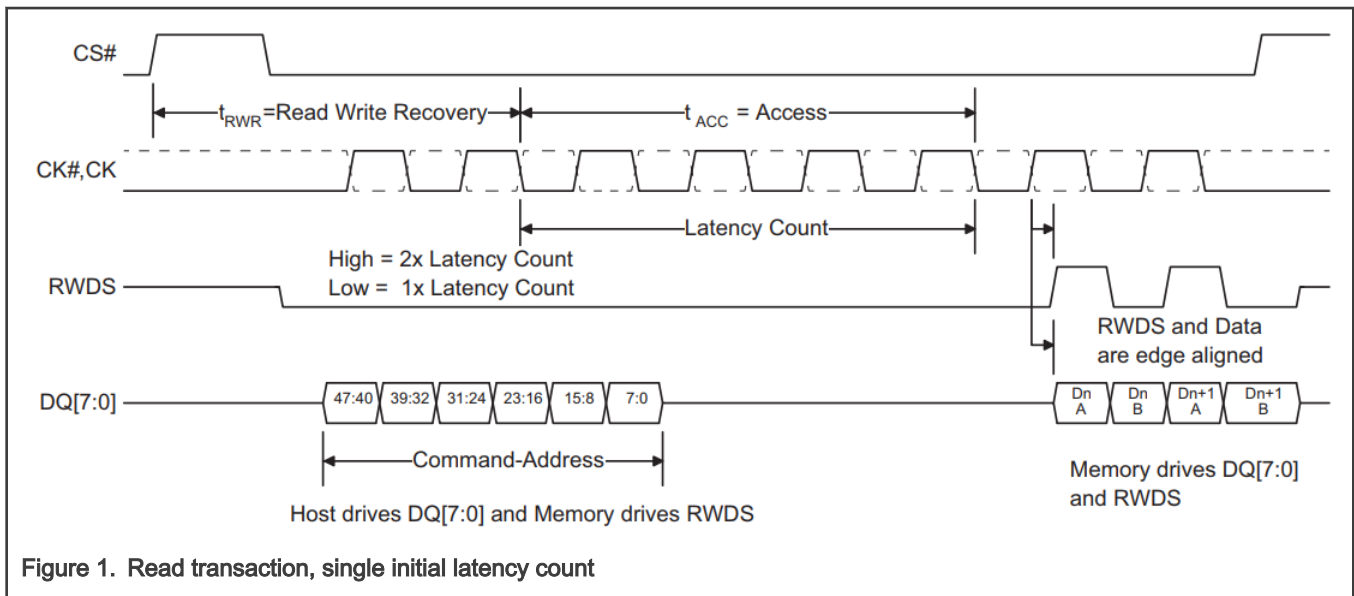
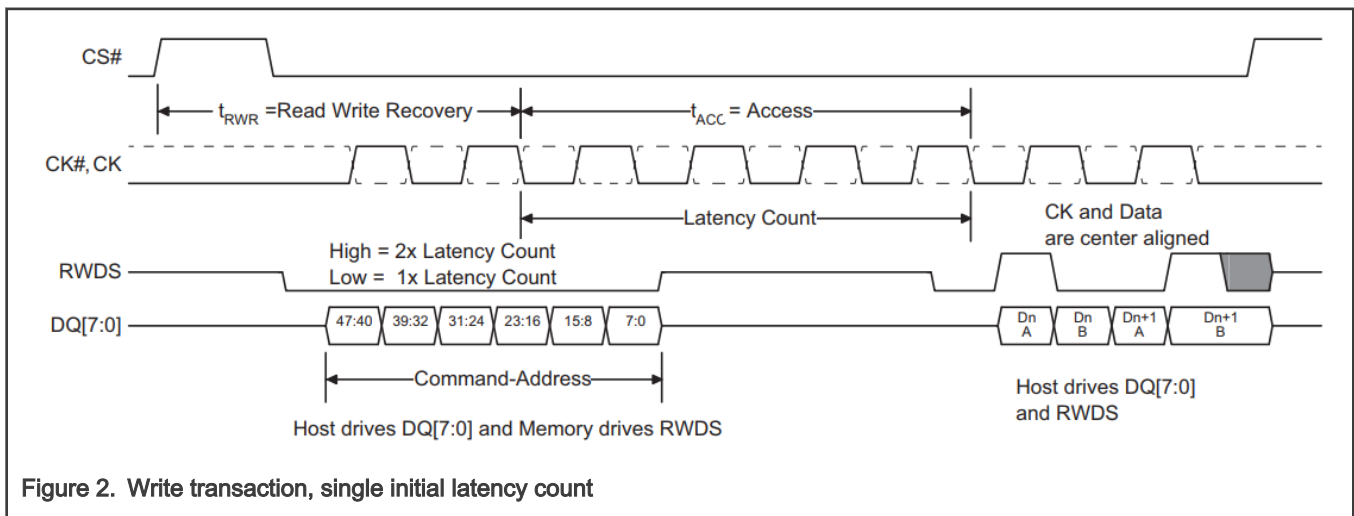


Figure 2 shows a write transaction with single latency count.



### 4 PSRAM overview

This chapter briefly describes the features of PSRAM devices used in this application note.

### 4.1 QSPI PSRAM

One PSRAM device used is [APS6404L-3SQR](#). It is the QSPI PSRAM from Apmemory vendor.

This PSRAM device features a high speed, low pin count interface. It has four Single Data Rate (SDR) I/O pins. It operates in Serial Peripheral Interface (SPI) or Quad Peripheral Interface (QPI) mode with frequencies up to 133 MHz. The data input (A/DQ) to the memory relies on clock (CLK) to latch all instructions, addresses, and data. It is most suitable for low-power and low-cost portable applications. It incorporates a seamless self-managed refresh mechanism. Hence it does not require the support of DRAM refresh from system host.

SPI/QPI PSRAM device is byte-addressable. The device recognizes the following commands specified by the various input methods.

Command	Code	SPI Mode (QE=0)					QPI Mode (QE=1)				
		Cmd	Addr	Wait Cycle	DIO	Max Freq.	Cmd	Addr	Wait Cycle	DIO	Max Freq.
Read	'h03	S	S	0	S	33	N/A				
Fast Read	'h0B	S	S	8	S	133/84*	Q	Q	4	Q	66
Fast Read Quad	'hEB	S	Q	6	Q	133/84*	Q	Q	6	Q	133/84*
Write	'h02	S	S	0	S	133/84*	Q	Q	0	Q	133/84*
Quad Write	'h38	S	Q	0	Q	133/84*	same as 'h02				
Enter Quad Mode	'h35	S	-	-	-	133	N/A				
Exit Quad Mode	'hF5	N/A					Q	-	-	-	133
Reset Enable	'h66	S	-	-	-	133	Q	-	-	-	133
Reset	'h99	S	-	-	-	133	Q	-	-	-	133
Wrap Boundary Toggle	'hC0	S	-	-	-	133	Q	-	-	-	133
Read ID	'h9F	S	S	0	S	33	N/A				
Remark: S = Serial IO, Q = Quad IO											

Figure 3. Command/Address latching truth table

### 4.2 Octal SPI PSRAM

Another PSRAM device used is [APS12808L-OBM-BA](#). It is the Octal SPI PSRAM from Apmemory vendor.

This PSRAM device has eight Double Data Rate (DDR) I/O pins. The pins transfer 2 bytes per one clock cycle and operate in SPI mode with frequencies up to 200 MHz.

Octal DDR PSRAM device is also byte-addressable. However, Memory accesses are required to start on even addresses (A[0]='0) and Mode Register accesses allow both even and odd addresses.

The Octal DDR PSRAM recognizes the following commands specified on the INST (Instruction) cycle defined by the Address/DQ pins.

	1st CLK		2nd CLK		3rd CLK	
Command						
Sync Read	00h	A3	A2	A1	A0	
Sync Write	80h	A3	A2	A1	A0	
Sync Read (Linear Burst)	20h	A3	A2	A1	A0	
Sync Write (Linear Burst)	A0h	A3	A2	A1	A0	
Mode Register Read	40h		×			MA
Mode Register Write	C0h		×			MA
Global Reset	FFh			×		
Remarks:	× = don't care ( $V_{IH}/V_{IL}$ )					
	A3 = unused address bits are reserved					
	A2 = RA[13:6]					
	A1 = RA[5:0],CA[9:8]					
	A0 = CA[7:0]					
	MA = Mode Register Address					

Figure 4. Command truth table

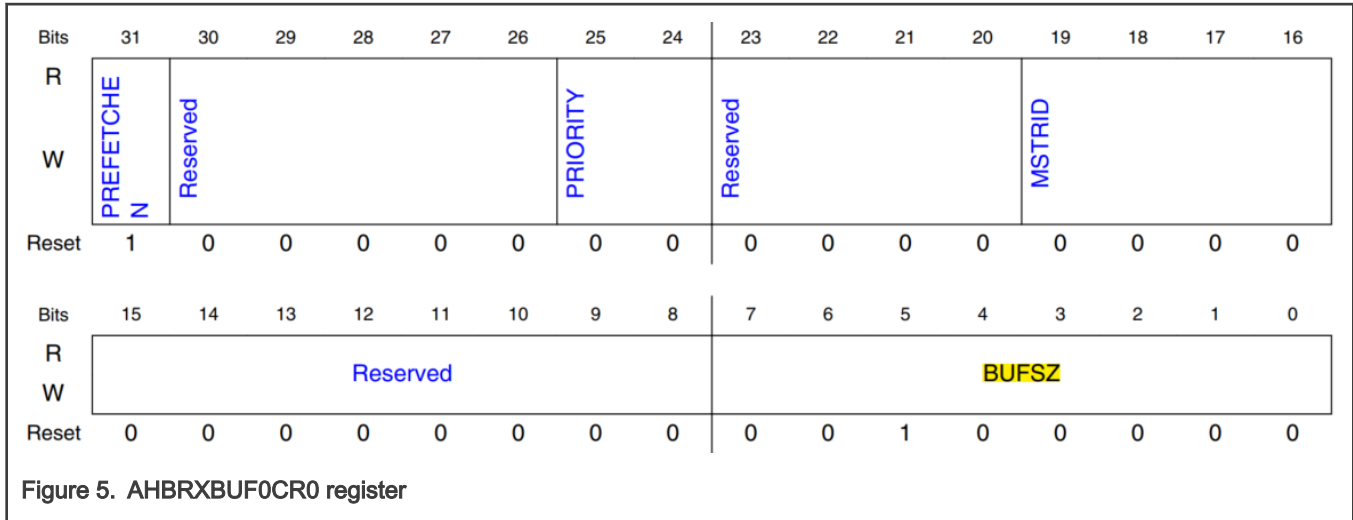
## 5 Advanced usage

This chapter describes advanced knowledge when using HyperRAM/PSRAM with i.MX RT series. It includes HyperRAM/PSRAM devices validated and some special configurations for FlexSPI and HyperRAM/PSRAM.

### 5.1 Prefetch

FlexSPI supports AHB RX prefetch buffer. To improve access latency during the read access and overall performance, FlexSPI is used to prefetch data when reading the external memory (for example, HyperRAM).

There are four buffers in AHB RX buffer for i.MX RT1050. The total size of AHB RX buffer is 1 Kbytes. The buffer size is flexibly configurable for each buffer in AHB RX buffer by register fields, `AHBRXBUF0CR0[BUFSZ]` - `AHBRXBUF3CR0[BUFSZ]`.



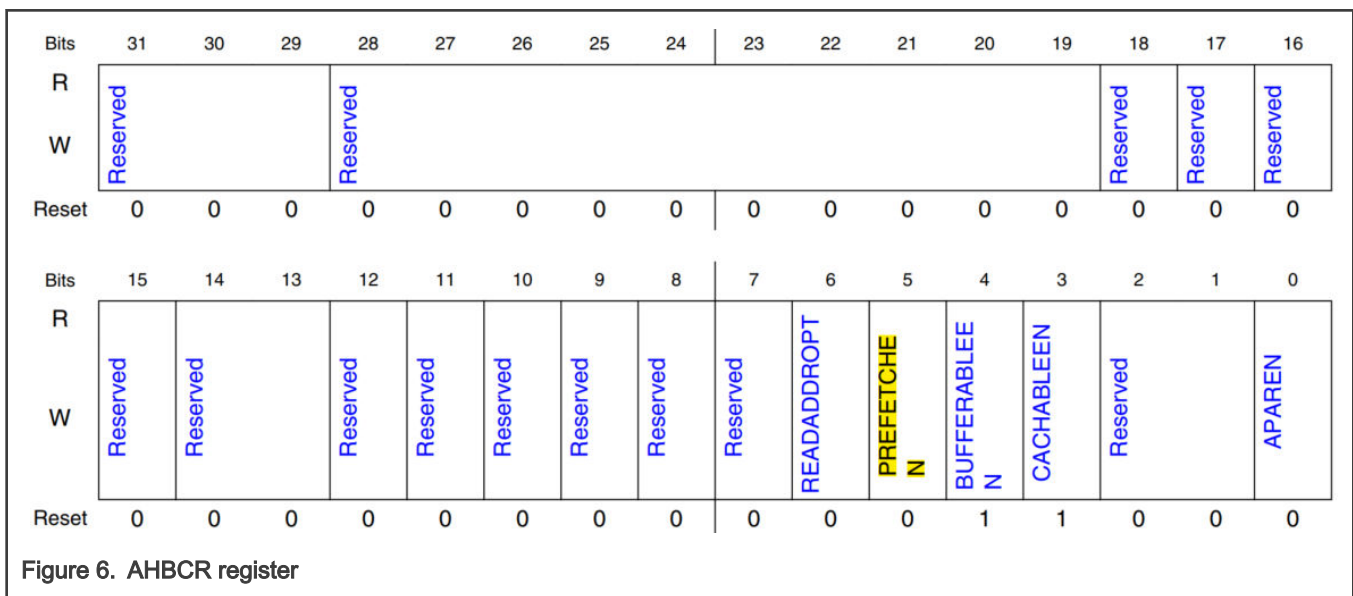
FlexSPI specifies different buffer size for different master. Some masters may have the dedicated prefetch buffer, which can optimize performance in some applications. The AHB RX buffer is assigned to different masters according to the register fields, `AHBRXBUF0CR0[MSTRID] - AHBRXBUF3CR0[MSTRID]`.

Some masters are assigned with dedicated master ID, as shown in [Table 1](#). The independent master ID is assigned to core, eDMA, and DCP. Other masters share one ID, say PXP, USB, and so on.

**Table 1. Master IDs**

Module	Master ID
Core platform	000b
eDMA	001b
DCP	010b
All others	011b

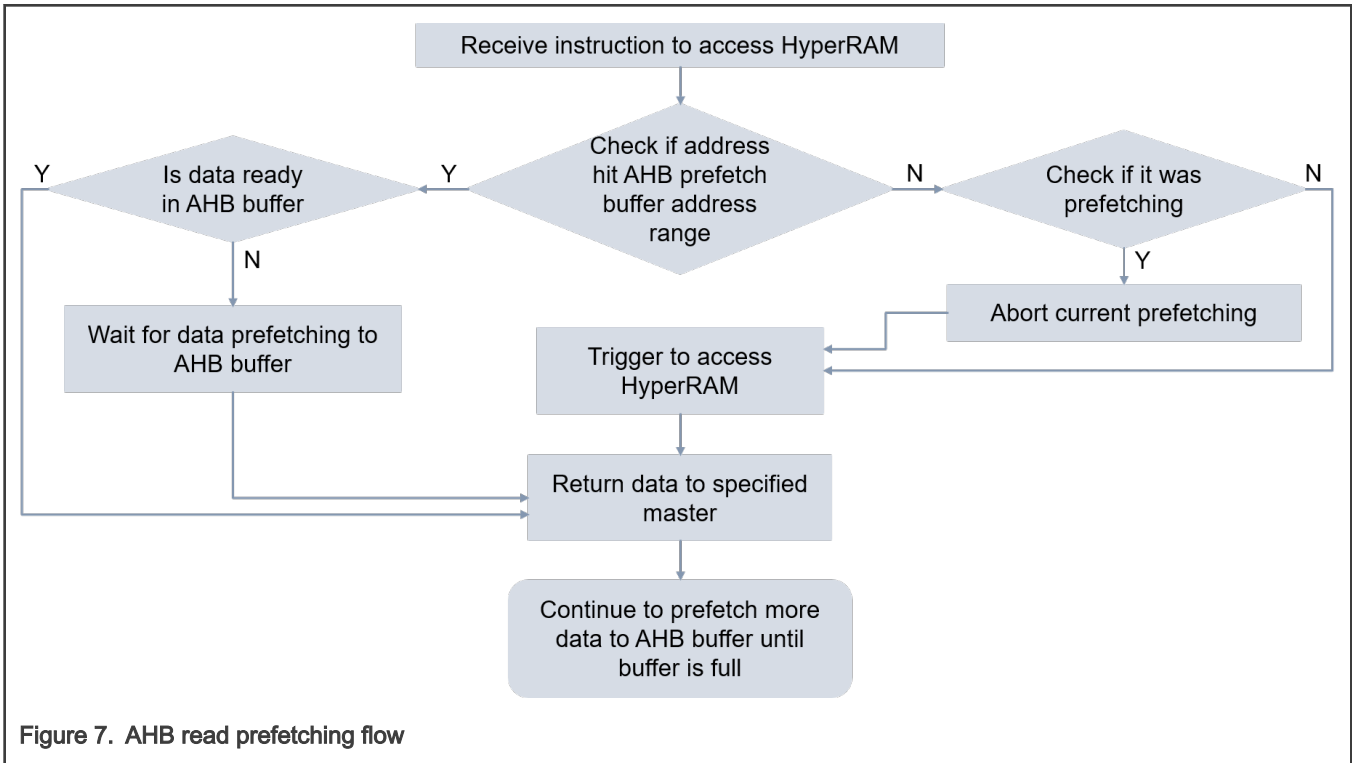
Modifying register fields can enable or disable AHB read prefetch, `AHBCR[PREFETCHEN]` and `AHBRXBUFxCR0[PREFETCHEN]`. Enable the AHB prefetch only when both `AHBCR[PREFETCHEN]=0x1` and `AHBRXBUFxCR0[PREFETCHEN]=0x1` (x is the AHB RX buffer ID for current AHB master). AHB buffer size determines the prefetch data size.



To describe the specific process of AHB prefetch, the following takes access to HyperRAM as an example.

When AHB prefetch is enabled, once receiving the request from the bus, it first checks whether the request matched the current AHB buffer address range. If yes, it directly returns the data. If not, it triggers to access HyperRAM to read new data to AHB buffer. After returning the required data to bus, it continues to prefetch data in following address to AHB buffer until the buffer is full. Any new IP command or AHB command request can abort AHB read prefetch when AHB is prefetching data.

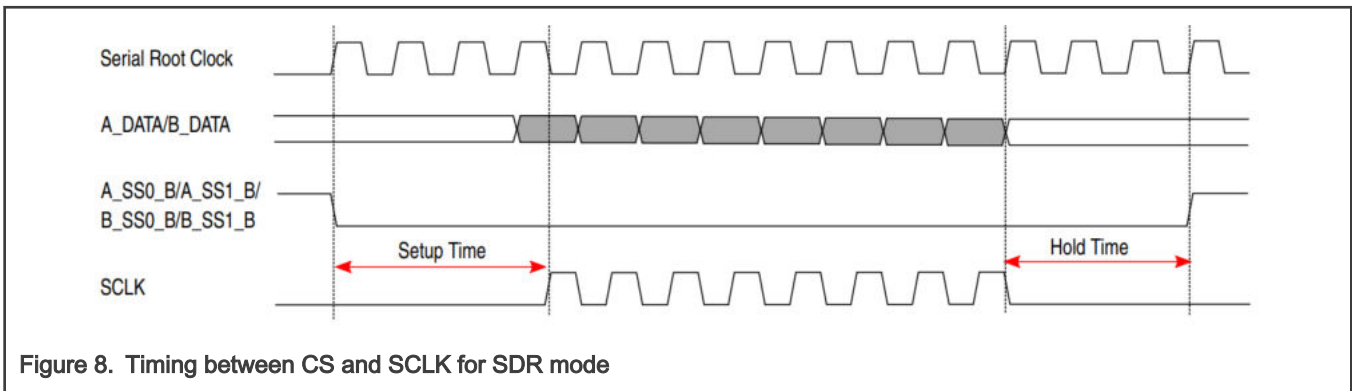
Figure 7 shows the general read prefetching flow.



## 5.2 TCSH/TCSS fields

FlexSPI should follow specific timing between Chip Selection (CS, on A\_SS0\_B/A\_SS1\_B/B\_SS0\_B/B\_SS1\_B) and SCLK signals.

For SDR mode, the delay from chip select assertion and the SCLK rising edge is (TCSS+0.5) cycles of serial root clock. The delay from SCLK falling edge and chip select de-assertion is TCSH cycles of serial root clock. Figure 8 indicates the timing relationship between chip selection and SCLK.



For DDR mode, the delay from chip selection assertion and SCLK rise edge is (TCSS+0.5) cycles of serial root clock. The delay from SCLK fall edge and chip selection deassertion is (TCSH+0.5) cycles of serial root clock. Figure 9 indicates the timing relationship between chip selection and SCLK.

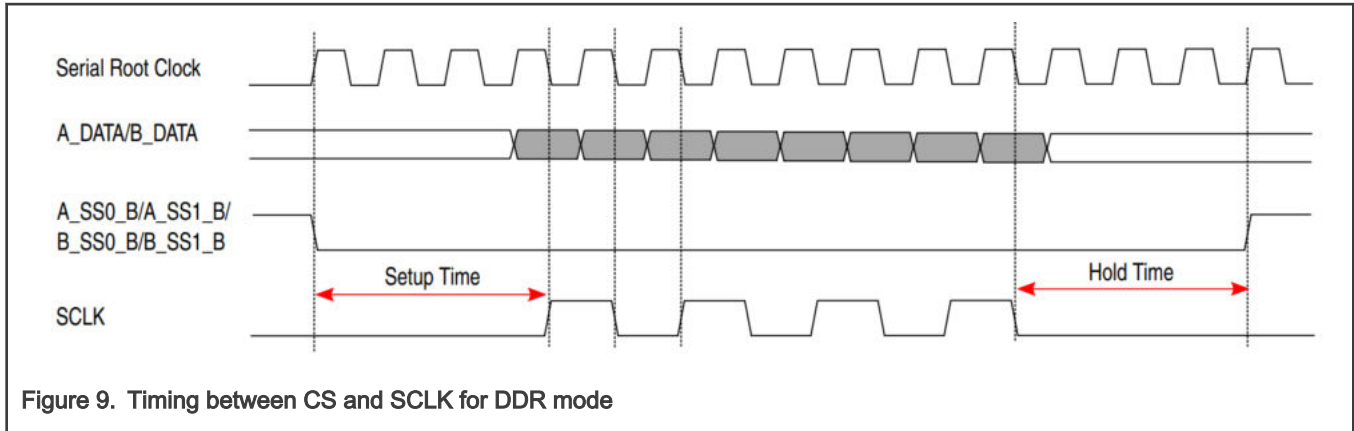


Figure 9. Timing between CS and SCLK for DDR mode

HyperRAM is the device using HyperBus interface and HyperBus interface supports DDR mode. Figure 9 shows the configuration of delay between CS and SCLK. APS6404L PSRAM supports SDR mode, while APS12808L PSRAM supports DDR mode.

TCSH and TCSS are fields of FLSHAxCR1/FLSHBxCR1 (x = 1,2) registers. Figure 10 shows the diagram of FLSHAxCR1/FLSHBxCR1 registers.

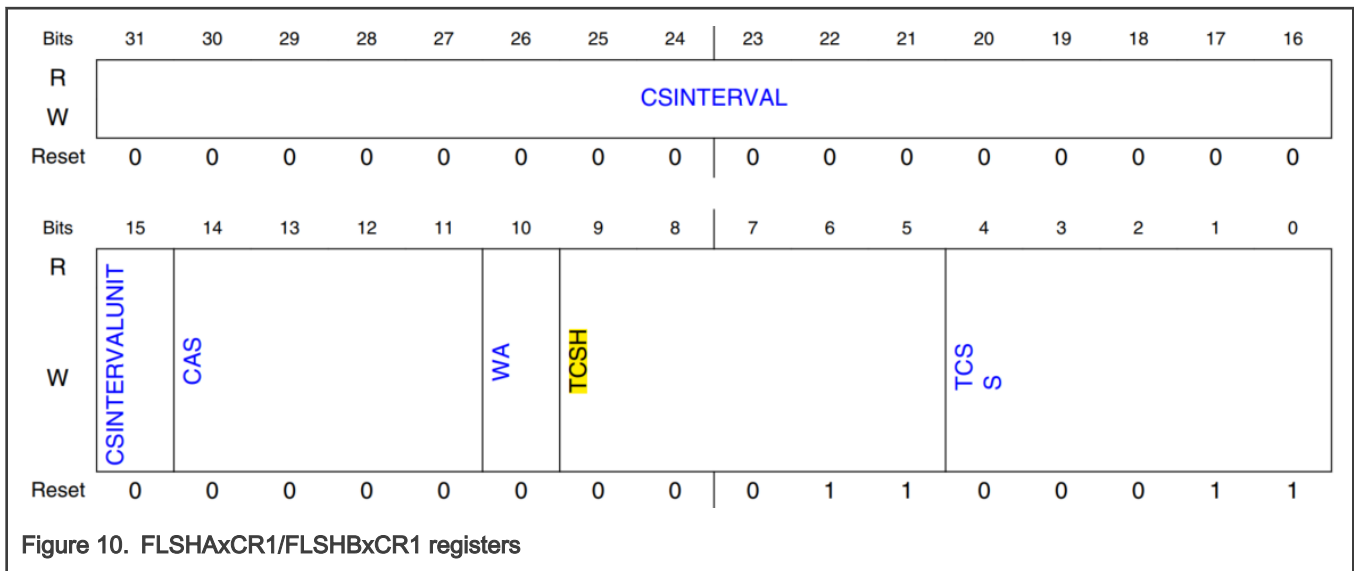


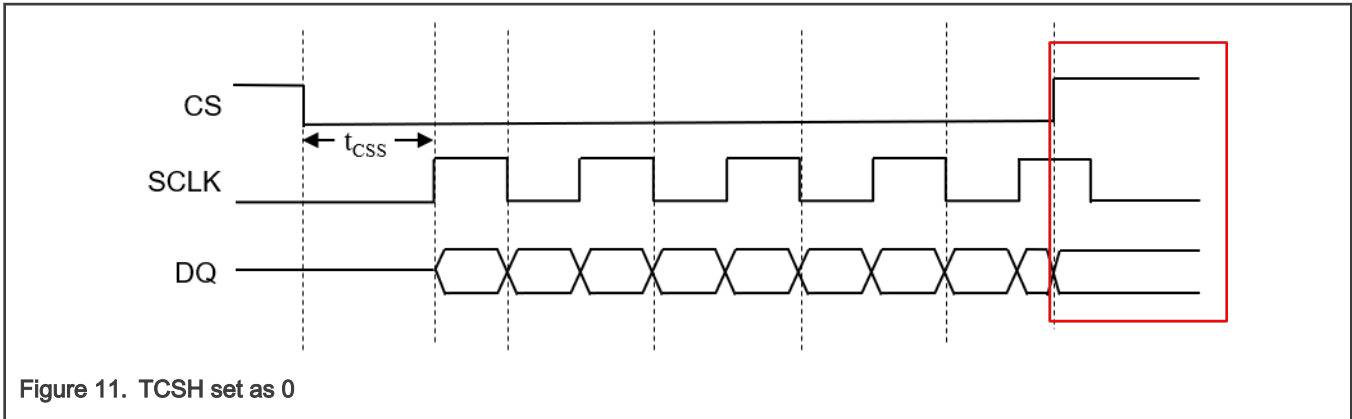
Figure 10. FLSHAxCR1/FLSHBxCR1 registers

For example, for HyperRAM device, TCSH and TCSS is equivalent to the  $t_{CSH}$  and  $t_{CSS}$  timing parameters. For example, Table 2 shows the related parameters in 7KS0642GAHI02 HyperRAM device.

Table 2. HyperRAM timing parameters

Parameter	Symbol	200 MHz		166 MHz		Unit
		Min.	Max.	Min.	Max.	
Chip select setup to next CK rising Edge	$t_{CSS}$	4.0	—	3	—	ns
Chip select hold after CK falling Edge	$t_{CSH}$	0	—	0	—	ns

In general, configure TCSH and TCSS values according to the timing parameters of HyperRAM, as shown in Table 2. However, as shown in Figure 11, if TCSH is set to 0, when aborting the prefetch (prefetch is enabled), reset the SCLK to default level after CS signal is deasserted. It may result in read errors.



Therefore, it is recommended to set TCSH and TCSS to the default values. Set both TCSH and TCSS to 3, as shown in Figure 10.

### 5.3 Distributed refresh interval

The DRAM array requires periodic refresh of all bits in the array. The host system can perform by reading or writing a location in each row within a specified time limit. The read or write access copies a row of bits to an internal buffer. At the end of the access, to recharge/refresh the bits in the row of DRAM memory cells, write back the bits in the buffer to the row in memory.

HyperRAM devices include self-refresh logic that refreshes rows automatically. A row automatically refreshes only when the host system is not actively reading or writing the memory. If a refresh is needed, the refresh logic waits for the end of any active read or write before performing a refresh. If a new read or write begins before the refresh is completed, the memory drives RWDS HIGH during the CA period. To allow the refresh operation to complete before starting the new access, the drive indicates that an additional initial latency time is required at the start of the new access.

Table 3 shows that the required refresh interval for the entire memory array varies with temperature of Cypress HyperRAM. It is the time within which all rows must be refreshed. Refresh all rows:

- either as a single batch of accesses at the beginning of each interval, in groups (burst refresh) of several rows at a time, spread throughout each interval.
- or as a single row refresh evenly distributed throughout the interval.

The self-refresh logic distributes single row refresh operations throughout the interval. The memory is not busy doing a burst of refresh operations for a long period, for example, the burst refresh delays host access for a long period.

Table 3. Array refresh interval per temperature

Device temperature (°C)	Array refresh interval (ms)	Array rows	Recommended $t_{CSM}$ (µs)
85	64	8192	4
105	16	8192	1

The distributed refresh method requires that the host does not do burst transactions to prevent the memory from doing the distributed refreshes when needed. It sets an upper limit on the length of read and write transactions so that the refresh logic can insert a refresh between transactions. This limit is called the CS# LOW maximum time ( $t_{CSM}$ ). The array refresh interval divided by the number of rows in the array determines the  $t_{CSM}$  value. To ensure that a maximum length host access start immediately before a distributed refresh does not miss a distributed refresh interval, reduce the calculation by half.

When using HyperRAM, the host system is required to respect the  $t_{CSM}$  value by ending each transaction before violating  $t_{CSM}$ . It can be done:

- either by host memory controller logic splitting long transactions when reaching the  $t_{CSM}$  limit.
- or by host system hardware or software not performing a single read or write transaction that is longer than  $t_{CSM}$ .

Otherwise, the HyperRAM fails to self-refresh, which leads to unpredictable errors.



To avoid violating  $t_{CSM}$ , follow the below suggestions:

- AHB RX buffer size, as defined by BUF<sub>SZ</sub> field in `AHBRXBUFCR0` register, cannot be too large. When prefetch is enabled, bigger AHB RX buffer size makes a single read access operation take too long time, which may violate  $t_{CSM}$ .
- Clock for FlexSPI and AHB Bus cannot be too small. Smaller clock frequencies make a single access operation take longer time, which may violate  $t_{CSM}$ .

## 5.4 Validated HyperRAM devices

HyperRAM devices from different vendors are tested to validate whether they can work well with i.MX RT series. [Table 4](#) lists the test results of all HyperRAM devices.

As shown in [Table 4](#), some HyperRAM devices, such as **7KS0641DPHI02**, seem to have an issue in the test. The failed devices enter a hard fault when enabling read prefetch of FlexSPI. When there is a prefetch abort in the middle of command/address cycle, these failed devices seem to have an issue. To avoid the issue, prevent the prefetch abort during command/address cycle. The prevention is hard to implement for FlexSPI. Therefore, it is not recommended to use these failed HyperRAM on i.MX RT series.

When using HyperRAM on i.MX RT series, use all devices with **PASS** results in [Table 4](#).

**Table 4. HyperRAM devices test results**

RT part number	HyperRAM vendor	HyperRAM part number	Results
PIMXRT1176DVMAA	Cypress	7KL0642DPHB02 (8 MB)	PASS
PIMXRT1064DVL6A	Cypress	7KS0642GAHI02 (8 MB)	PASS
PIMXRT1052DVL6B	Cypress	7KS0641DPHI02 (8 MB)	FAIL
PIMXRT1064DVL6A	Cypress	7KS0641DPHI02 (8 MB)	FAIL
PIMXRT1064DVL6A	Winbond	W956x8MBYA (8 MB)	PASS
PIMXRT1064DVL6A	ISSI	IS66WVH32M8DALL (32 MB)	PASS
PIMXRT1176DVMAA	ISSI	IS66WVH32M8DALL (32 MB)	PASS

## 5.5 PSRAM test

This section describes PSRAM devices test on i.MX RT series and summarizes the PSRAM devices currently verified on RT series.

### 5.5.1 QSPI PSRAM

For QSPI PSRAM, all i.MX RT series can support well.

One PSRAM device [APS6404L-3SQR](#) from Apmemory vendor has been tested on i.MX RT1050. The test result is that this PSRAM can work well with i.MX RT1050.

### 5.5.2 Octal SPI PSRAM

For Octal SPI PSRAM, i.MX RT1020/RT1050/RT1060 have some limitations to support.

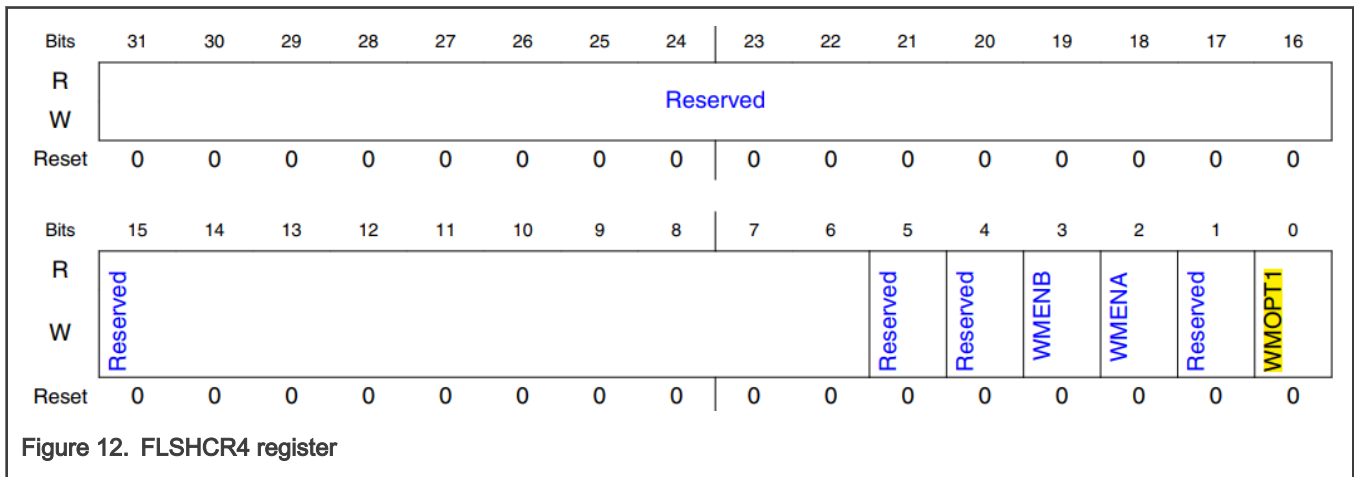
As mentioned above, memory accesses of Octal SPI PSRAM are required to start on even addresses ( $A[0]=0$ ). However, FlexSPI controller of RT1020/RT1050/RT1060 has one limitation that cannot support this access method of Octal SPI PSRAM.

Fortunately, after making specific updates for FlexSPI IP, RT1010 and RT1170 products can support Octal SPI PSRAM. To confirm, test with a PSRAM device, [APS12808L-OBM-BA](#), on i.MX RT1170.

To support Octal SPI PSRAM, pay attention to the following two points in FlexSPI configuration:

- For AHB read from PSRAM, set READADDROP bit of AHBCR register to 1, as shown in [Figure 12](#). It removes AHB burst start address alignment limitation.

- For AHB write to PSRAM, set WMOPT1 bit of FLSHCR4 register to 0, as shown in [Figure 12](#). It removes AHB write burst minimal length limitation for Octal SPI PSRAM.



The test result shows that RT1170 can support Octal SPI PSRAM well.

### 5.5.3 Supported PSRAM

[Table 5](#) lists validated and supported PSRAM devices on i.MX RT series. For QSPI PSRAM devices, all RT series can support well, while for Octal SPI PSRAM, only RT1010/RT1170 and all RTyyy products can support well.

Table 5. PSRAM support table

PSRAM interface	PSRAM vendor	PSRAM part number	RT product	Support or not
QSPI	Apmemory	APS6404L-3SQR	RT1050	Yes
	—	—	All RTxxxx	Yes
	—	—	All RTyyy	Yes
Octal SPI	Apmemory	APS12808L-OBM-BA	RT1170	Yes
	—	—	RT1010	Yes
	—	—	All RTyyy	Yes
	—	—	RT1020/RT1050/ RT1060	No

## 6 References

1. *i.MX RT1050 Processor Reference Manual* (document [MXRT1050RM](#))
2. *How to Enable HyperRAM with i.MX RT* (document [AN12239](#))

## 7 Revision history

Rev.	Date	Description
2	29 November 2021	Updated <a href="#">Validated HyperRAM devices</a>
1	30 June 2021	Updated <a href="#">Validated HyperRAM devices</a>
0	October 2020	Initial release

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